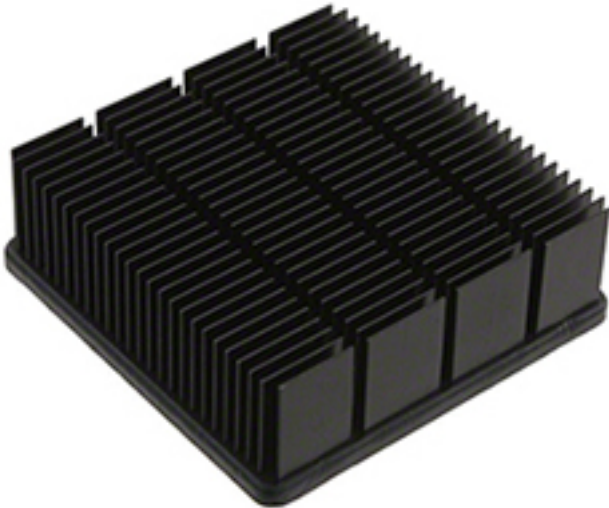


CTS Heat Sinks with Low Thermal Resistance

WDD Staff



[CTS Electronic Components, Incorporated](#)

[1] (Elkhart, IN) [[NYSE: CTS](#) [2]] has announced a full line of heat sink products that are convenient and easy to use, while maintaining an exceptional thermal performance. Features include:

- Applicability for BGA, PGA, PLCC, QFP, and other IC packages.
- A low-profile, thin fin design.
- A height that ranges from 6.3 to 32.6 mm.
- A thermal resistance of 1.9°C/W @ 200 LFPM convection flow conditions.
- An adhesive tape or clip to help attach to integrated circuits.
- A shear strength @ 100°C is 36 psi.

For more information visit <http://www.ctscorp.com/components> [1].

Source URL (retrieved on 01/30/2015 - 5:39pm):

<http://www.wirelessdesignmag.com/product-releases/2013/02/cts-heat-sinks-low-thermal-resistance?qt-blogs=0>

Links:

[1] <http://www.ctscorp.com/components>

[2]

<https://www.google.com/finance?q=NYSE%3A+CTS&ei=z8osUejgDMYqqQGkFA>